



AURUNA® 8400 Gold Nickel Electrolyte

High speed electrolyte for hard gold plating

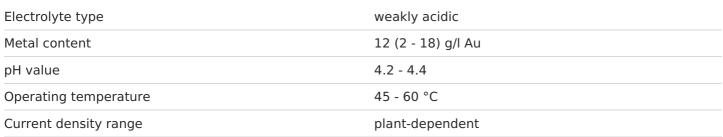
AURUNA® 8400 is used for the deposition of hard gold coatings in special high-speed equipment. The electrolyte is weakly acidic, citrate-free and has a wide working range with simple bath maintenance.

The deposited coatings are high-brightness, low-porosity, solderable, hard and abrasion-resistant, and exhibit consistently low contact resistance. They are therefore ideally suited for electrical components such as contacts, plugs and connectors on printed circuit boards.

AURUNA® 8400 was developed for high-speed gold plating in selective plating lines and continuous reel-to-reel systems. It shows stable long-term behavior even with strong electrolyte movement (flow, spray) and high current densities. AURUNA® 8400 can also be used as a pregold electrolyte.

The optional use of AURUNA® Inhibitor 2 offers the possibility of reduced gold consumption of up to 15%. The inhibitor results in sharp edge delineations - thus reducing the run-out zone width. Of course, the coating properties remain unaffected. The inhibitor can be removed without residue after coating by activated carbon cleaning.





plant dan and ant up to 12 um /min

Coating characteristics

Coating	Gold nickel
Purity	approx. 99.7 wt.% Au, approx. 0.3 wt.% Ni
Colour of deposit	yellow
Brightness	bright to highly bright
Hardness of deposit	approx. 130 - 190 HV
Max. coating thickness	10 μm
Density of the coating	approx. 17 g/cm³

Advantages

- Very high plating speeds
- Lower gold content possible
- Exceptionally wide working range
- Stable long-term behavior
- Easy electrolyte maintenance
- Excellent coating properties

Applications

- Connectors
- Electrical contacts
- Connector strips on printed circuit boards

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